

Getting Started With MSP MCUs With CapTivate™ Technology

MSP430FR2633, MSP430FR2533, MSP430FR2632, MSP430FR2532

This getting started guide provides information on where to find documentation and collateral for MSP MCUs with CapTivate™ technology.

1 Introduction

The latest documentation for MSP MCUs with CapTivate technology is [available online](#). The following links are shortcuts to specific topics in the online version.

- Introduction
 - [Capacitive sensing basics](#)
 - [Introduction to CapTivate technology](#)
 - [Differences between MSP MCUs with capacitive touch I/Os and CapTivate technology](#)
- Getting started with CapTivate technology
 - Silicon
 - [MSP430FR263x, MSP430FR253x data sheet](#)
 - [MSP430FR2633 errata sheet](#)
 - [MSP430FR2533 errata sheet](#)
 - [MSP430FR2632 errata sheet](#)
 - [MSP430FR2532 errata sheet](#)
 - Tools
 - [CapTivate MCU development kit](#)
 - [CAPTIVATE-BSWP self-capacitance sensor board](#)
 - [CAPTIVATE-PHONE mutual-capacitance sensor board](#)
 - [CAPTIVATE-PROXIMITY proximity sensor board](#)
 - [CapTivate technology with metal-touch capacitive sensor](#)
 - Software
 - [CapTivate design center GUI](#)
 - [CapTivate software library](#)
 - Installation Procedure
 - [For TI Code Composer Studio™ software](#)
 - [For IAR Embedded Workbench™ software](#)
 - [CapTivate technology out-of-the-box experience](#)

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- Advance design guides
 - [CapTIvate technology hardware design guide](#)
 - [Designing for ultra-low power](#)
 - [Designing for noise immunity](#)
 - [Designing for moisture](#)
 - [Designing for proximity](#)
 - [IEC reference design](#)

Revision History

Changes from November 7, 2015 to February 11, 2016**Page**

- Changed link on "Differences between MSP MCUs with capacitive touch..." list item [1](#)
- Changed links in the "Silicon" list item [1](#)

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

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